



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC105N10LSF G	Issued	17. February 2022
MA#	MA005698719		
Package	PG-TDSON-8-1	Weight*	122.80 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.418	4.41	4.41	44118	44118
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		308	
	non noble metal	copper	7440-50-8	37.762	30.76	30.80	307510	307910
wire	non noble metal	copper	7440-50-8	0.028	0.02	0.02	229	229
encapsulation	organic material	carbon black	1333-86-4	0.078	0.06		634	
	plastics	epoxy resin	-	5.528	4.50		45016	
	inorganic material	silicondioxide	60676-86-0	33.323	27.14	31.70	271367	317017
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11821	11821
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1348	1348
solder	non noble metal	tin	7440-31-5	0.081	0.07		660	
	noble metal	silver	7440-22-4	0.101	0.08		825	
	non noble metal	lead	7439-92-1	3.868	3.15	3.30	31499	32984
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		182	
	noble metal	silver	7440-22-4	1.289	1.05		10501	
	non noble metal	copper	7440-50-8	22.292	18.15	19.23	181531	192269
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.22	9.23	92184	92304
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com